

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER																																																														
Application Number :	10/680783																																																														
Confirmation Number:	5859																																																														
First Named Applicant:	William Jones																																																														
Attorney Docket Number:																																																															
Art Unit:																																																															
Examiner:																																																															
Search string:	( 3681171 or 4827867 or 5009738 or 6221781 or 6306564 or 6497239 or 20030005948 ).pn																																																														
<p><u>Certification:</u> This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.</p>																																																															
<h2>US Patent Documents</h2> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>3681171</td><td>1972-08-01</td><td>Toku Hojo et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>4827867</td><td>1989-05-09</td><td>Takei et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>5009738</td><td>1991-04-23</td><td>Gruenwald et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>6221781</td><td>2001-04-24</td><td>Siefering et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>5</td><td>6306564</td><td>2001-10-23</td><td>Mullee</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>6</td><td>6497239</td><td>2002-12-24</td><td>Farmer et al.</td><td>B2</td><td></td><td></td></tr></tbody></table>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	3681171	1972-08-01	Toku Hojo et al.					2	4827867	1989-05-09	Takei et al.					3	5009738	1991-04-23	Gruenwald et al.					4	6221781	2001-04-24	Siefering et al.	B1				5	6306564	2001-10-23	Mullee	B1				6	6497239	2002-12-24	Farmer et al.	B2		
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Examiner Name	Date